

TYPE: BM63*** Series

PACKAGE: HSDIP25/HSDIP25VC

【 Reliability Test Result】

ITEM	TEST METHOD		DURATION	n	Pn
Resistance to soldering heat<*2>	Soak into solder tub (260±5°C)	EIAJ ED4701-302	10s	5	0
Resistance to soldering heat<*2>	Heat by solder iron (350±10°C)	EIAJ ED4701-302	4s	5	0
Pressure Cooker<*1>	Storage at 121°C / 100% /2atm	-	96hours	5	0
Temperature Cycling<*1>	-40°C (30min) / 125°C (30min)	EIAJ ED4701-105	100cycles	5	0
High Temperature Storage	Ta=125°C	EIAJ ED4701-201	1000hours	5	0
Low Temperature Storage	Ta=-40°C	EIAJ ED4701-202	1000hours	5	0
Temperature Humidity Storage<*1>	Ta=60°C / RH=90%	EIAJ ED4701-103	1000hours	5	0
High Temperature Operation	Apply the specified voltage (Vce=510V) at Ta=125°C	EIAJ ED4701-101	1000hours	5	0
Intermittent operating life	Intermittent operating life at ΔTj=100°C	EIAJ ED4701-106	5000cycles	5	0

【Strength Test Result】

Terminal pulling strength	Control terminal: 5N, Power terminal: 10N	EIAJ ED4701-400	10sec	5	0
Terminal bending strength	Control terminal: 2.5N, Power terminal: 5N, 90°	EIAJ ED4701-400	2times	5	0
Mounting torque	Mounting screw M3, 0.78N · m	-	10sec	5	0
Free fall	Height 75cm, Woodboard	-	3times	5	0
Solderability	Dipping temperature 250±5°C	EIAJ ED4701-303	5sec	5	0
Thermal shock	0°C(5min)/100°C(5min)	EIAJ ED4701-307	10cycle	5	0
Electro Static Discharge	C=100p,R=1.5kΩ,3times,±2000V HBM (Human Body Model)	EIAJ ED4701-304	-	5	0
Latch Up	Pulse current injection, trigger pulse current ±100mA	EIAJ ED4701-306	-	5	0

<*1> Soldering Heat examination is executed for the precondition.

<*2>Moisture soaking treatment Standard : 85°C 85% 168h